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July 2016

## FCPF067N65S3

# N-Channel SuperFET<sup>®</sup> III MOSFET 650 V, 44 A, 67 m $\Omega$

#### **Features**

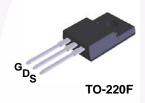
- $700 \text{ V } @ \text{ T}_{\text{J}} = 150 \text{ }^{\text{O}}\text{C}$
- Typ.  $R_{DS(on)} = 59 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 78 nC)
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 715 pF$ )
- 100% Avalanche Tested
- RoHS Compliant

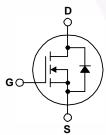
### **Applications**

- Telecom / Sever Power Supplies
- · Industrial Power Supplies
- UPS / Solar

## **Description**

SuperFET® III MOSFET is Fairchild Semiconductor's brandnew high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET is very suitable for various power system for miniaturization and higher efficiency.





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		FCPF067N65S3	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		650	V
V	Cata to Course Valtage	- DC	±30	V
$V_{GSS}$	Gate to Source Voltage	- AC (f>1 Hz	) ±30	] V
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)	44*	^
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)	28*	A
I <sub>DM</sub>	Drain Current	- Pulsed (Note	110*	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy	2) 1160	mJ	
I <sub>AR</sub>	Avalanche Current	8.8	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		0.46	mJ
dv/dt	MOSFET dv/dt		100	V/ns
αν/αι	Peak Diode Recovery dv/dt (Note 3)		3) 20	V/IIS
D	Pawer Discipation	$(T_C = 25^{\circ}C)$	46	W
$P_D$	Power Dissipation  - Derate Above 25°C		0.37	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperate	Operating and Storage Temperature Range		
T <sub>L</sub>	Maximum Lead Temperature for \$	Soldering, 1/8" from Case for 5 Seconds	300	°С

<sup>\*</sup>Drain current limited by maximum junction temperature.

#### Thermal Characteristics

Symbol	Parameter	FCPF067N65S3	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	*C/VV

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF067N65S3	FCPF067N65S3	TO-220F	Tube	N/A	N/A	50 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Chara	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
BV <sub>DSS</sub>	Drain to Source Breakdown voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 150^{\circ}\text{C}$	700	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.72	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V	-	-	1	
IDSS		$V_{DS} = 520 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	2.2	-	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 4.4$ mA	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$		59	67	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 22 \text{ A}$		29	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0 V,	-	3090	-	pF
C <sub>oss</sub>	Output Capacitance	f = 1 MHz	-	68	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	715	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$	-	104	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 22 A,	-	78	-	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	18	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	30	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω

#### **Switching Characteristics**

	_						
t <sub>d(on)</sub>	Turn-On Delay Time			- /	26	1	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 22 \text{ A},$		- /	52	1	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$		-/	89	-	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4)	-	16	-	ns

#### **Source-Drain Diode Characteristics**

Is	Maximum Continuous Drain to Source Dioc	Maximum Continuous Drain to Source Diode Forward Current		-	44	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	110	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 22 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 22 A,	-	435	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	9.2	-	μС

#### Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{AS}$  = 8.8 A,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3.  $I_{SD} \le 22$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le 380$ V, starting  $T_J = 25^{\circ}C$ .
- 4. Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

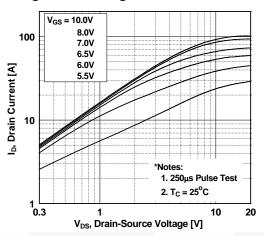


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

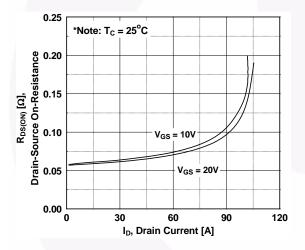


Figure 5. Capacitance Characteristics

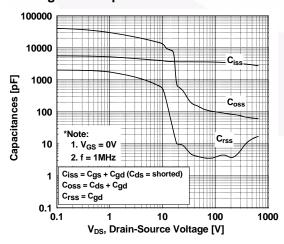


Figure 2. Transfer Characteristics

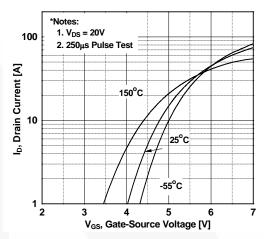


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

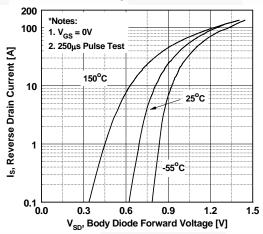
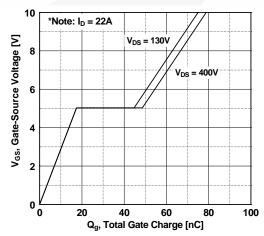


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

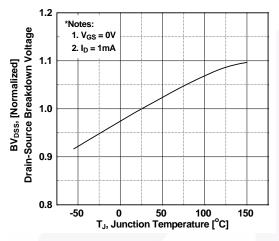


Figure 9. Maximum Safe Operating Area

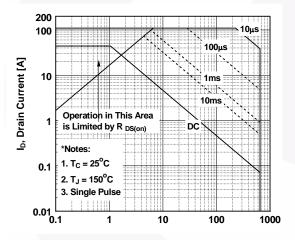


Figure 11. Eoss vs. Drain to Source Voltage

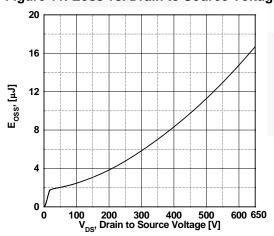


Figure 8. On-Resistance Variation vs. Temperature

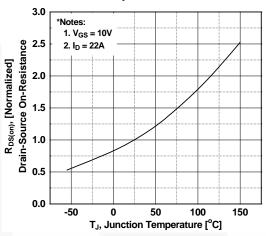
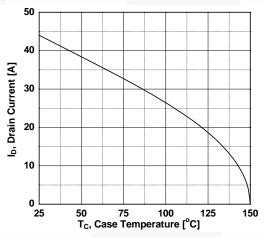
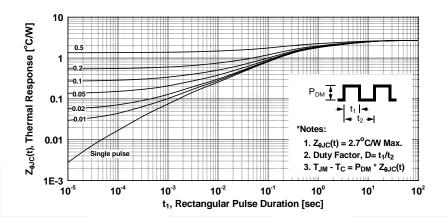


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



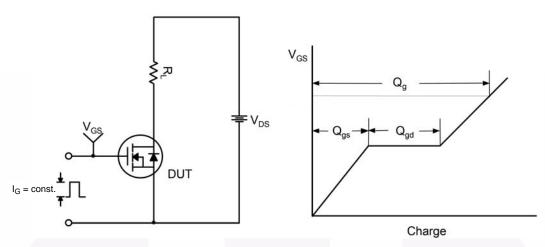


Figure 13. Gate Charge Test Circuit & Waveform

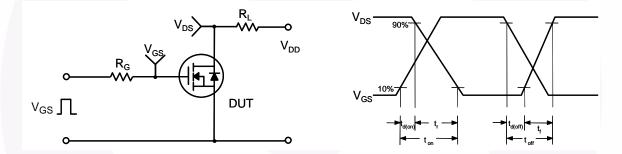


Figure 14. Resistive Switching Test Circuit & Waveforms

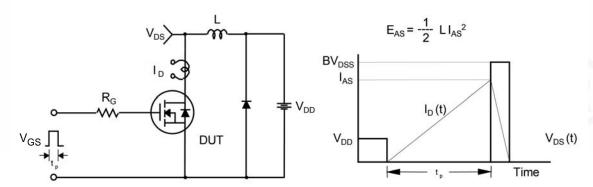


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

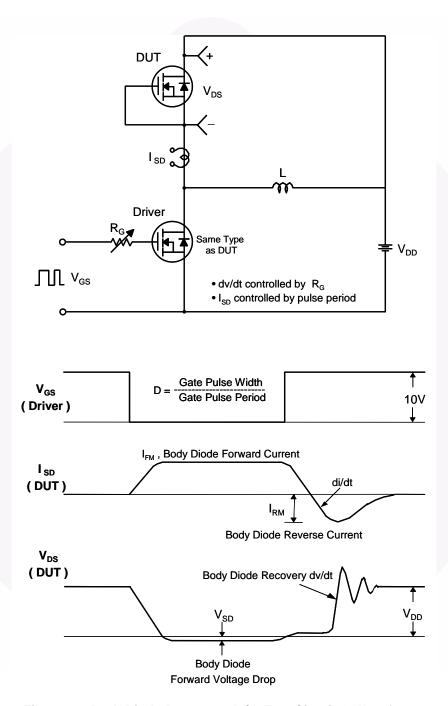
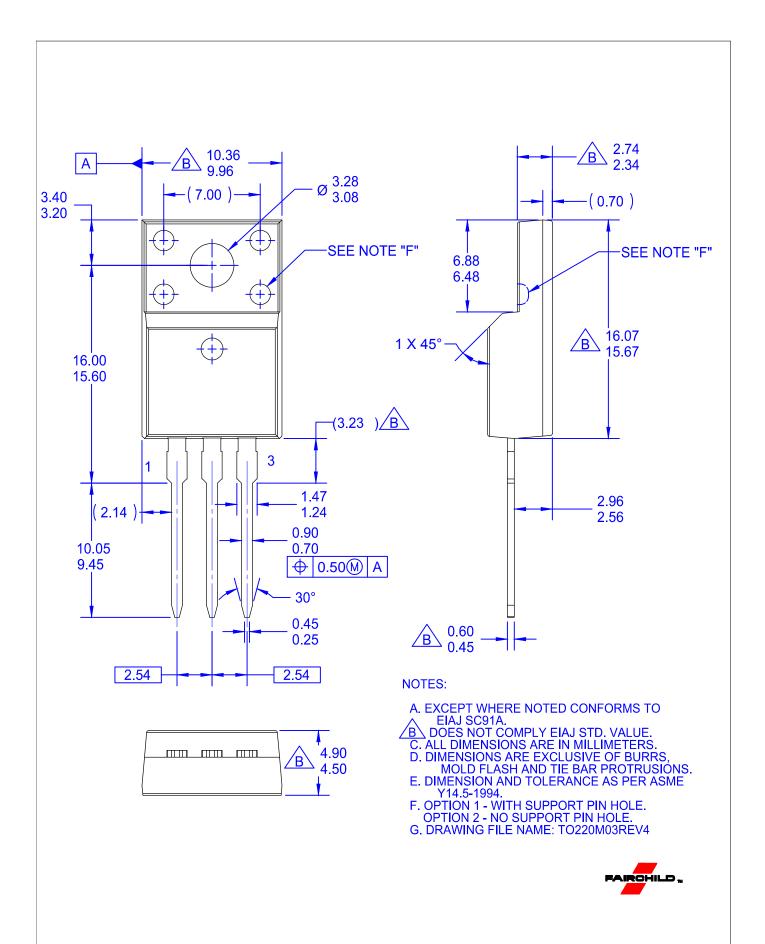


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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